

MICROELECTRONIC STANDARDS (MS)

Contents

MS-001	Plastic DIP .300" Row Spacing
MS-002	Leadless Chip Carrier .050" Type A
MS-003	Leadless Chip Carrier .050" Type B
MS-004	Leadless Chip Carrier .050" Type C
MS-005	Leadless Chip Carrier .050" Type D
MS-006	Leaded Chip Carrier .050" Type A
MS-007	Leaded Chip Carrier .050" Type A
MS-008	Leaded Chip Carrier .050" Type B
MS-009	Leadless Chip Carrier .040"
MS-010	Plastic DIP .400" Row Spacing
MS-011	Plastic DIP .600" Row Spacing
MS-012	Plastic SO .150" Body Width
MS-013	Plastic SO .300" Body Width
MS-014	Single Layer Chip Carrier .040"
MS-015	Ceramic DIP .300" - .900" Spacing
MS-016	Plastic chip Carrier Rect. .050"
MS-017	Ceramic PGA .100" Pitch Cavity Down
MS-018	Square Plastic Chip Carrier .050" Pitch
MS-019	R-PDIP-T Dual in-line (Shrink .070") Plastic Family .300" Row Spacing
MS-020	R-PDIP-T Dual in-line (Shrink .070") Plastic Family .600" Row Spacing
MS-021	R-PDIP-T Dual in-line (Shrink .070") Plastic Family .750" Row Spacing
MS-022	Metric Plastic Quad Flat Pack 1.0, 0.8, 0.65 mm
MS-023	Plastic SOJ
MS-024	TSOP II 10.16 mm Body
MS-025	Thin Small Outline Pkg. 7.62 mm Body
MS-026	Plastic Quad Flatpack 1.0 & 1.4 mm thick
MS-027	PDSO-J
MS-028	Rectangular Plastic Ball Grid Array 1.27 mm
MS-029	Fine Pitch QFP 2.6 mm footprint
MS-030	.300" wide CDIP
MS-031	.400" wide CDIP
MS-032	.600" wide CDIP
MS-033	Ceramic Dual Flatpack Family, .050" Pitch
MS-034	Plastic Square Ball Grid Array Family